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NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6020AK uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- V_{DS} =60V,I_D =20A
 R_{DS(ON)} <35mΩ @ V_{GS}=10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

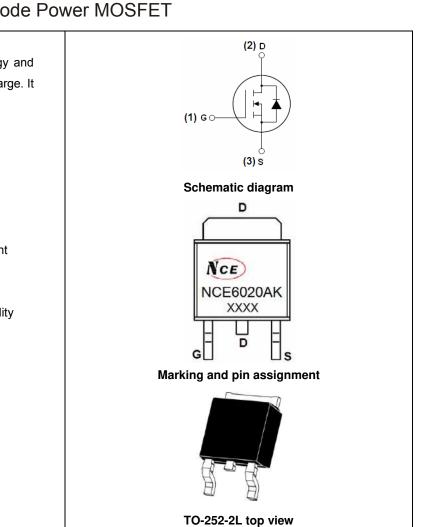
100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6020AK	NCE6020AK	TO-252-2L	-	-	-

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	Ι _D	20	А
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	14	А
Pulsed Drain Current	I _{DM}	60	А
Maximum Power Dissipation	PD	45	W
Derating factor		0.3	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	72	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	°C







Thermal Characteristic

Thermal Resistance, Junction-to-CaseNote 2)R _{0JC} 3.3°C/W

Electrical Characteristics (T_c=25 $^{\circ}$ Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.2	1.6	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	27	35	mΩ
Forward Transconductance	g fs	V _{DS} =5V,I _D =5A	11	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}		-	500	-	PF
Output Capacitance	C _{oss}	V _{DS} =30V,V _{GS} =0V, F=1.0MHz		60	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHZ	-	25	-	PF
Switching Characteristics (Note 4)	1					•
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	tr	V _{DD} =30V,I _D =2A,R _L =6.7Ω	-	2.6	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10V, R_{G} =3 Ω	-	16.1	-	nS
Turn-Off Fall Time	t _f		-	2.3	-	nS
Total Gate Charge	Qg	N/ 201/1 / 5A	-	47		nC
Gate-Source Charge	Q _{gs}	V_{DS} =30V,I _D =4.5A,	-	6		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	14		nC
Drain-Source Diode Characteristics	1					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	I _S		-	-	20	А
Reverse Recovery Time	trr	TJ = 25°C, IF =20A	-	35	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	53	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25 $^{\circ}$ C, VDD=30V, VG=10V, L=0.5mH, Rg=25 Ω

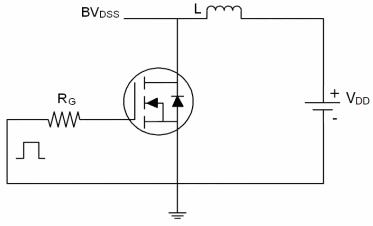


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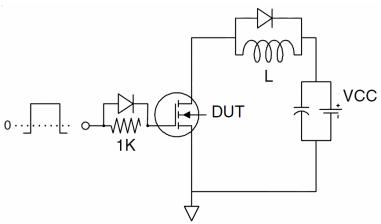




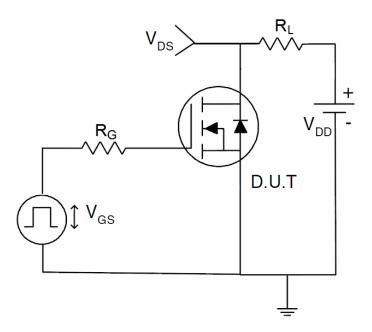
Test Circuit 1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





V_{GS}=10V

I_D=10 A

50

75

V_{DS}=30V

20

125°C

0.4

30

25°C

0.6

0.8

40

50

I_D=10A

100

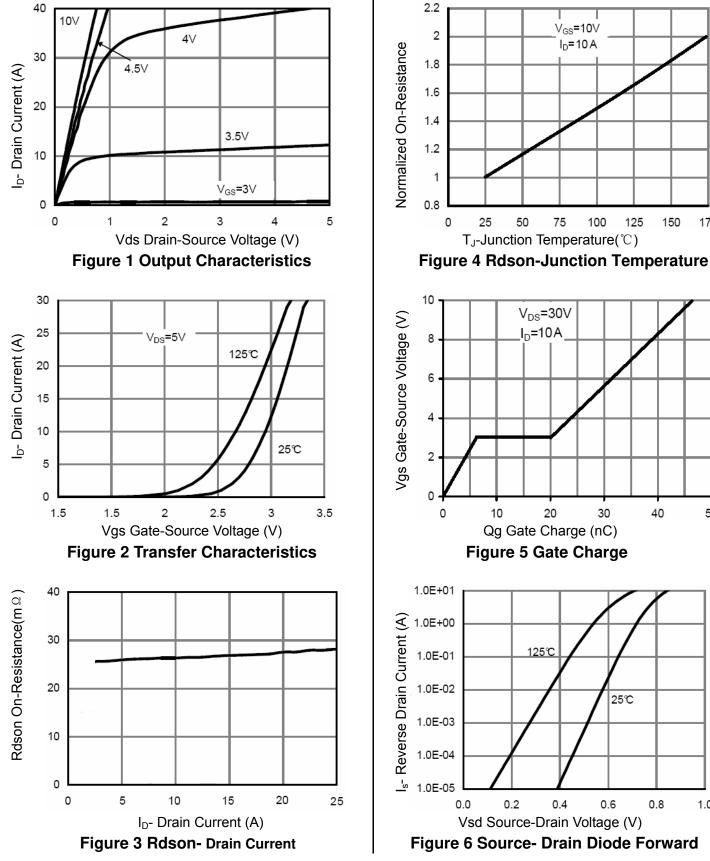
125

150

175







1.0



800

600

400

200

0

0

C.

10

20

30

Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds

40

50

60

C Capacitance (pF)

I_D- Drain Current (A)

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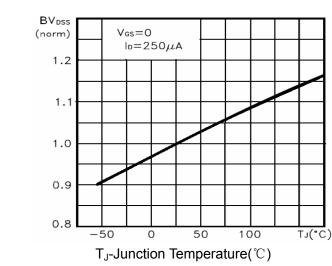
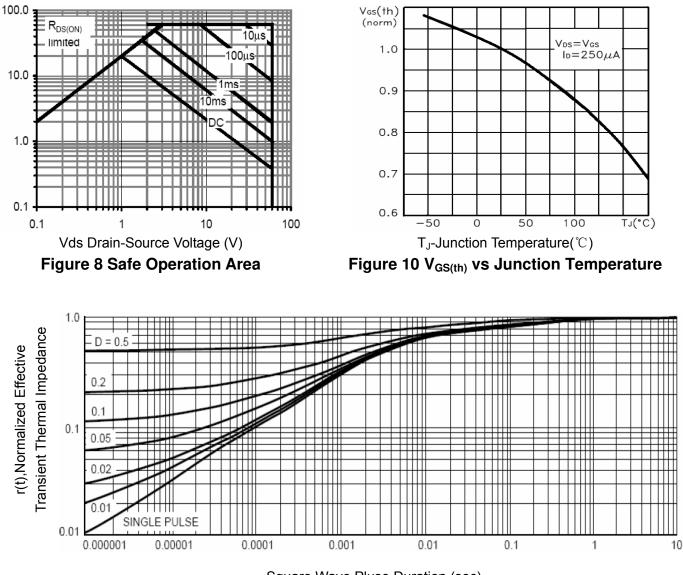
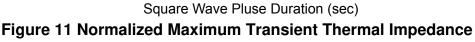


Figure 9 BV_{DSS} vs Junction Temperature



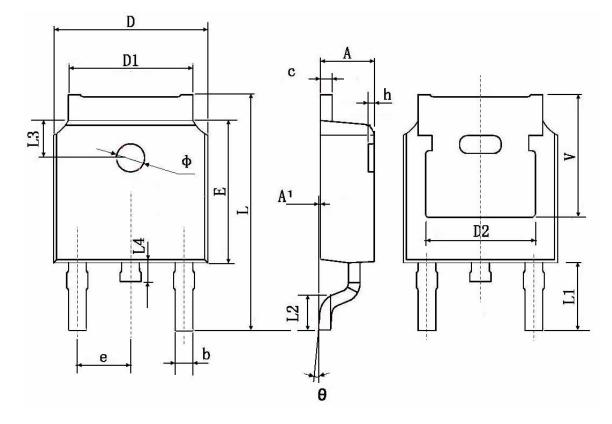




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TO-252 Package Information



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		







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